


**TRANSMITTAL**

Electronic Version v1.1

Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>INTEGRATION OF BARRIER LAYER AND SEED LAYER</b>	
Application Number :	09/965370	
Date :	2001-09-26	
First Named Applicant:	Mr. Chung Hua	
Confirmation Number:	6507	
Attorney Docket Number:	APPM6303	
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Submitted By: Mrs. Ya-Fen Chen Registered Number: 51,553		Elec. Sign. /Ya-Fen Chen/ Sign. Capacity Agent

Documents being submitted:	Files
us-ids	APPM6303-usidst.xml
	us-ids.dtd
	us-ids.xsl
us-fee-sheet	APPM6303-usfees.xml
	us-fee-sheet.xsl
	us-fee-sheet.dtd
Comments	